

LNPTTM THERMOCOMPTM COMPOUND Z1C00VI

DESCRIPTION

LNP THERMOCOMP Z1C00VI compound is based on Polyphenylene Ether / Polystyrene (PPE/PS) blend containing proprietary fillers. Added features of this grade include: Ultra-Low Dielectric Constant and Loss Tangent for Laser Direct Structuring (LDS), High HDT, Low Warpage, Excellent Surface Finishing and Chemical Resistant.

GENERAL INFORMATION

Features	Chemical Resistance, Low Warpage, Dielectrics, Laser Direct Structuring, High temperature resistance, Impact resistant, No PFAS intentionally added
Fillers	Unreinforced
Polymer Types	Polyphenylene Ether + PS (PPE+PS)
Processing Techniques	Injection Molding

INDUSTRY

Automotive
Consumer
Electrical and Electronics
Industrial

SUB INDUSTRY

Automotive Interiors
Personal Accessory
Mobile Phone - Computer - Tablets
Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yld, Type I, 50 mm/min	70	MPa	ASTM D638
Tensile Stress, brk, Type I, 50 mm/min	52	MPa	ASTM D638
Tensile Strain, yld, Type I, 50 mm/min	4.5	%	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	8	%	ASTM D638
Tensile Modulus, 50 mm/min	2700	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	110	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	2700	MPa	ASTM D790
Tensile Stress, yield, 50 mm/min	70	MPa	ISO 527
Tensile Stress, break, 50 mm/min	55	MPa	ISO 527
Tensile Strain, yield, 50 mm/min	4.5	%	ISO 527
Tensile Strain, break, 50 mm/min	9	%	ISO 527
Tensile Modulus, 1 mm/min	2800	MPa	ISO 527
Flexural Stress, break, 2 mm/min	115	MPa	ISO 178
Flexural Modulus, 2 mm/min	2800	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, notched, 23°C	40	J/m	ASTM D256
Izod Impact, unnotched, 23°C	600	J/m	ASTM D4812
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
Izod Impact, unnotched 80*10*4 +23°C	50	kJ/m ²	ISO 180/1U
THERMAL ⁽¹⁾			

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CHEMISTRY THAT MATTERS™

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	155	°C	ISO 75/Bf
PHYSICAL ⁽¹⁾			
Density	1.11	g/cm ³	ISO 1183
Mold Shrinkage, flow ⁽²⁾	0.5 – 0.7	%	SABIC method
ELECTRICAL ⁽¹⁾			
Dielectric Constant, 1.1 GHz	2.65	-	SABIC method
Dielectric Constant, 1.9 GHz	2.65	-	SABIC method
Dielectric Constant, 10 GHz	2.65	-	SABIC method
Dissipation Factor, 1.1 GHz	0.0012	-	SABIC method
Dissipation Factor, 1.9 GHz	0.0014	-	SABIC method
Dissipation Factor, 10 GHz	0.0020	-	SABIC method
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120	°C	
Drying Time	3 – 5	Hrs	
Melt Temperature	270 – 320	°C	
Nozzle Temperature	280 – 320	°C	
Front - Zone 3 Temperature	280 – 310	°C	
Middle - Zone 2 Temperature	270 – 300	°C	
Rear - Zone 1 Temperature	260 – 290	°C	
Mold Temperature	100 – 140	°C	
Back Pressure	10	MPa	
Screw Speed	100	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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